IN THE CLAIMS

1. (Currently Amended) Assembly process of at least one electronic component ~~(1)~~ including sensibly flat conductive areas ~~(3)~~ that are connected to conductive tracks ~~(6')~~ placed on the surface of a generally flat insulating support called a substrate ~~(5)~~ characterized by the following steps:

- placing the substrate ~~(5)~~ on a work surface, the face including conductive tracks ~~(6')~~ being oriented upwards,

- placing the electronic component ~~(1)~~ into a cavity ~~(7)~~ of the substrate ~~(5)~~ situated in a zone including the conductive tracks ~~(6')~~, the conductive areas ~~(3)~~ of the component ~~(1)~~ coming into contact with the corresponding tracks ~~(6')~~ of the substrate ~~(5)~~,

- applying a layer of insulating material ~~(8)~~ which extends at the same time on the component ~~(1)~~ and at least on a substrate zone surrounding said component ~~(1)~~, in such a way that the electric connection between the conductive areas ~~(3)~~ and conductive tracks ~~(6')~~ is ensured by the pressure of the insulating layer ~~(8)~~ on the component ~~(1)~~.

2. (Currently Amended) Process according to claim 1 ~~characterized in that~~ wherein the electronic component ~~(1)~~ is made up of a chip ~~(2)~~ provided with contacts on one of its faces, said contacts being set off on a conductive film constituting the contact areas that extend the contacts of the chip ~~(2)~~, the opposite face of the chip being coated by an insulating material ~~(4)~~.

3. (Currently Amended) Process according to claim 1 ~~characterized in that~~ wherein the layer of insulating material is made up of a first substrate ~~(5)~~ including a cavity ~~(7)~~ into which the component ~~(1)~~ is inserted by its coated face, the contact areas ~~(3)~~ of said component ~~(1)~~ connecting with corresponding conductive areas ~~(6)~~ of a second substrate ~~(9)~~ placed on the work surface.

4. (Currently Amended) Process according to claim 1 ~~characterized in that~~ wherein the electronic component ~~(1)~~ is made up of a chip ~~(2)~~ provided with contacts on one of its faces, said contacts being set off on a conductive film constituting the contact areas ~~(3)~~ that extend the contacts of the chip ~~(2)~~.

5. (Currently Amended) Process according to claims 1 ~~and 4 characterized in that~~ wherein the electronic component is made up of a chip provided with contacts on one of its faces, said contacts being set off on a conductive film constituting the contact areas that extend the contacts of the chip, the layer of insulating material is made up of a first substrate ~~(5)~~ including a cavity ~~(7)~~ in which the chip ~~(2)~~ of the component ~~(1)~~ is inserted, the contact areas ~~(3)~~ of said component ~~(1)~~ being applied against the surface of the substrate ~~(5)~~ connecting with corresponding conductive areas ~~(6)~~ of a second substrate ~~(9)~~ placed on the work surface.

6. (Currently Amended) Process according to ~~claims 1 and 4~~claim 5 ~~characterized in that~~ wherein the cavity ~~(7)~~ of the component ~~(1)~~ is obtained by heating the chip ~~(2)~~ of the component ~~(1)~~ then pushing said chip ~~(2)~~ into the substrate ~~(5)~~ material by means of adequate tooling, the contact areas ~~(3)~~ of said component ~~(1)~~ being applied against the surface of the substrate (5).

7. (Currently Amended) Process according to claim 1 ~~characterized in that~~ wherein the electronic component ~~(1)~~ is made up of a chip ~~(2)~~ provided with sensibly flat contacts on one of its faces.

8. (Currently Amended) Process according to claim 7 ~~characterized in that~~ wherein the layer of insulating material is made up of a first substrate ~~(5)~~ including a cavity ~~(7)~~ into which the chip ~~(2)~~ is inserted, the contacts of said chip showing on the surface level of the substrate are connected with corresponding conductive areas ~~(6)~~ of a second substrate ~~(9)~~ placed on the work surface.

9. (Currently Amended) Process according to claim 1 ~~characterized in that~~ wherein the cavity ~~(7)~~ of the component ~~(1)~~ is made up by milling or by stamping a window.

10. (Currently Amended) Process according to claim 8 ~~characterized in that~~ wherein the cavity ~~(7)~~ of the chip ~~(2)~~ is obtained by heating then pressing said chip ~~(2)~~ into the material of the substrate ~~(5)~~ by means of adequate tooling, the contact areas of said chip ~~(2)~~ showing on the surface level of the substrate.

11. (Currently Amended) Process according to claim 1 ~~characterized in that~~ wherein the electronic component ~~(1)~~ is made up of a module including a set of flat contacts on one of its faces and on the opposite face conductive areas linked to each contact of the set.

12. (Currently Amended) Process according to claims 1 ~~and 11 characterized in that~~ wherein the module is inserted into a cavity ~~(7)~~ provided with a window cut into a first substrate ~~(5)~~ with a thickness approximately equal to that of the module, the set of flat contacts shows on the surface level of said substrate ~~(5)~~ and the conductive areas of the opposite face lean against the conductive tracks ~~(6')~~ of a second substrate ~~(9)~~ assembled on the first substrate ~~(5)~~.

13. (Currently Amended) Process according to claim 12, ~~characterized in that~~ wherein at least one module or a supplementary chip ~~(2)~~ is mounted in one of the substrates ~~(5, 9)~~, said module including conductive areas ~~(3)~~ connected by pressure on the corresponding conductive tracks ~~(6')~~ of either of the substrates ~~(5, 9)~~.

14. (Currently Amended) Process according to claims ~~3 and~~ 13 ~~characterized in that~~ wherein it includes a supplementary step of gluing and pressing the assembly formed by the superposition of the substrates ~~(5, 9)~~.